

Product Change Notice

Issue Date: 17 December 2007**Change Type:**

Avago Technologies has qualified new material source for scrambler which will be used in Annunciator (SIP series).

Parts Affected:

HLCP-A100	HLMP-2516
HLCP-A100-BC000	HLMP-2523
HLCP-B100	HLMP-2550
HLCP-B100-BC000	HLMP-2550-FG000
HLMP-2300	HLMP-2566
HLMP-2300-EF000	HLMP-2566-F0051
HLMP-2316	QLCP-A146
HLMP-2323	QLCP-B248
HLMP-2350	QLMP-2389
HLMP-2350-EF000	QLMP-2447
HLMP-2366	QLMP-2589
HLMP-2400	HLMP-2450
HLMP-2400-EF000	HLMP-2450-EF000
HLMP-2416	HLMP-2500
HLMP-2423	HLMP-2500-FG000

Description and Extent of Change:

The selected material is alternate source used for scrambler mold compound of Through Hole Annunciator (SIP series), which will serve the same functionality as the existing scrambler.

Reasons for Change:

This is to ensure continuous supply, improve the quality and reliability of the Through Hole Annunciator (SIP series).

Effect of Change on Fit, Form, Function, Quality, or Reliability:

There will be no change on form, fit, function, quality or reliability on the finished products.

Effective Date of Change:

Any SIP series products with manufacturing date starting 17th March 2008 (WW11'08) will be using the new scrambler material. There will be a period where Avago may be shipping mixed parts from old and new scrambler. However for all products after the cut off date, scrambler will be using Valox material. There will be no mix between new and old scrambler within 1 box.

Avago tentatively plan to change Linear Array series and DIP series products scrambler material from Sept 2008 of manufacturing date, after feasibility study.

Qualification Data:

Qualification data has been generated and approved.
These are the main qualification data for reference.

Qualification vehicle: 0.8 SIP

Item	Test Type	Condition	Total sample size ^[2]	Test Criteria	Test Result
1	2XTTW -> Air-to-air Temperature Shock (ATMSK)	-40 to 110°C, 20 mins dwell, 0 minutes transfer	22	No open/short, No crack	Passed 100cycles
2	2XTTW -> Temperature Cycle (TMCL)	-40 to 85°C, 15 mins dwell, 5 minutes transfer	200	No open/short, No crack	Passed 500cycles
3	High Temperature Storage Life test (HTSL)	125°C	22	No open/short, No crack	Passed 500hrs
4	High Temperature Storage Life test (HTSL)	100°C	22	No open/short, No crack	Passed 500hrs
5	Temperature Humidity Storage Life test (WHTSL)	85°C and 85% RH	22	No open/short, No crack	Passed 500hrs
6	Multiple TTW	Pb-Free Profile, 260°C max peak	22	No open/short, No crack	Passed 10cycles
7	Solder Heat Resistance (SHR)	260°C +/- 5°C for 5 sec	22	No open/short, No crack	Passed 10cycles
8	Steam Aging test	100°C / 100% RH	22	No open/short, No crack	Passed 336hrs
9	Mechanical Shock	1500g 0.5ms; 3 shock each axis	22	No open/short, No crack	Passed 5cycles

These changes have been reviewed and approved by Avago Technologies engineers and managers per Avago Technologies procedure: Change Control and Customer Notification, A-5962-6052-80.

Please contact your Avago Technologies field sales engineer or Contact Center (<http://www.avagotech.com/contact/>) for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.